LISTING OF THE CLAIMS:

- 1. (Currently Amended) A substrate having at least two metallized polymer studs for soldered connections to a wiring and having conductor runs which lead away from the polymer studs on a lower face of the substrate, each of the polymer studs having at least one step-in order to form an end with at least one projection extending beyond an end surface of the rest of the stud to form a step at the end of the stud.--
- 2. (Previously Presented) The substrate according to claim 1, wherein the projection is a cylindrical projection which is arranged concentrically with respect to the polymer stud.
- 3. (Currently Amended) The A substrate according to claim 2, wherein having at least two metallized polymer studs for soldered connections to a wiring and having conductor runs which lead away from the polymer studs on a lower face of the substrate, each of the polymer studs having a step in order to form a cylindrical projection which is arranged concentrically with respect to the polymer stud, the cylindrical projection has having a diameter of between 100μm and 300μm, and a height of between 25μm and 250μm.
- 4. (Previously Presented) The substrate according to claim 1, wherein the polymer studs are provided with two projections forming two steps.
- 5. (Previously Presented) The substrate according to claim 1, wherein the polymer studs are provided with a number of projections arranged at a distance from one another on the step.

Claim 6 (cancelled).

7. (New) The substrate according to claim 1, wherein the projection is an annular projection.